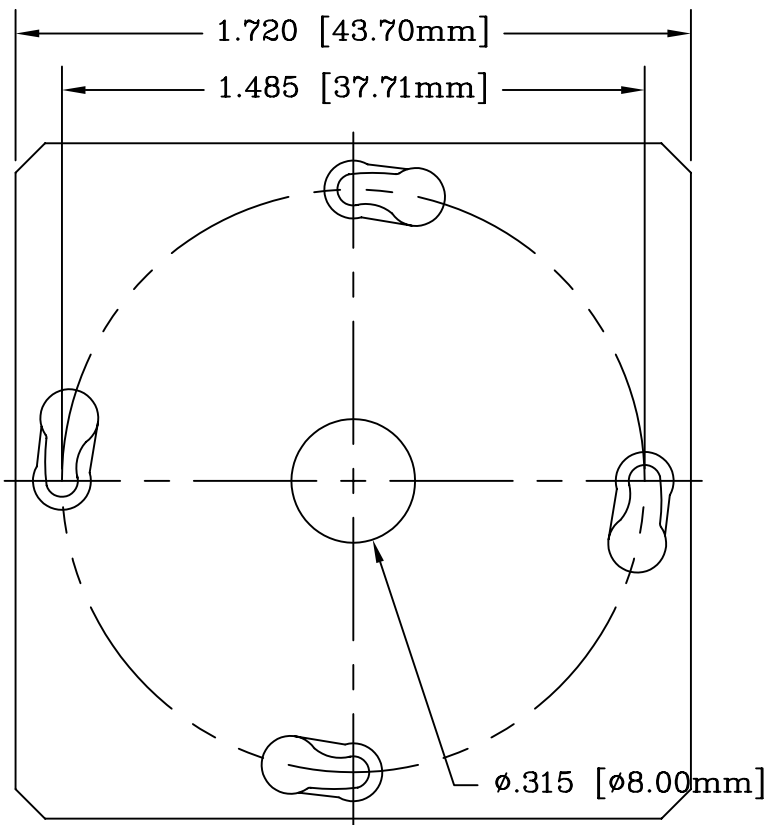
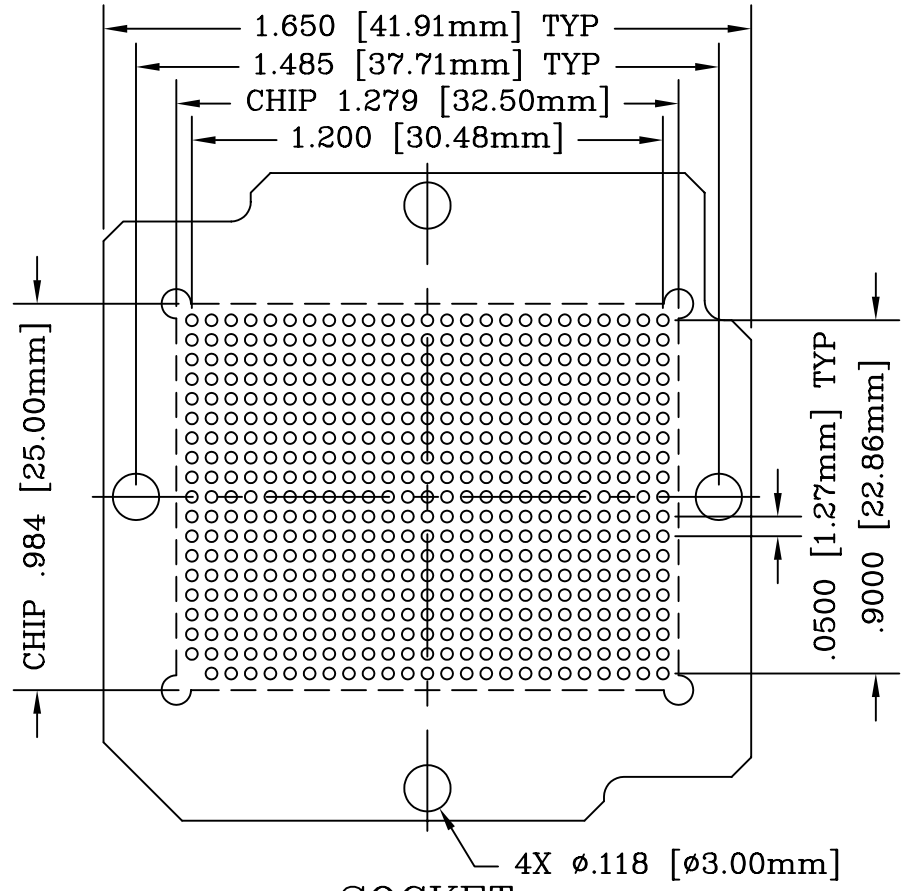


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	05/24/04	H.N.

SKT1779



RETENTION FRAME

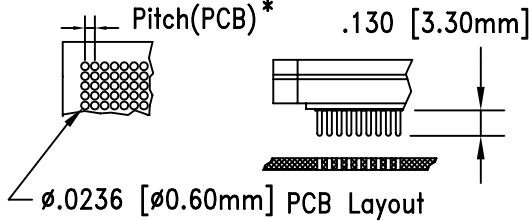
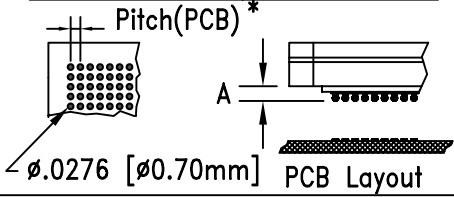


SOCKET

RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE	RAISED SMT STYLE
XX = (-SM)	XX = (-RC)
YY = (-30)	YY = (-29)

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET)
YY = (-70)



30= standard SMD ("A" = .047 [1.20mm])  
 29= raised SMD ("A" = .197 [5.00mm])

PIN DIAMETER FOR:  
 -70(ET) = .0177 [0.45mm]

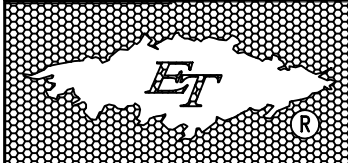
BALL DIAMETER FOR:  
 -29(RC) = .026 [0.66mm]  
 -30(SM) = .026 [0.66mm]

\* All Dimensions Are Nominal For A .050 [1.27mm] Pitch BGA Package

PACKAGE SPECIFICATIONS

PIN COUNT	= 474
LEAD PITCH	= 1.27mm
GRID SIZE	= 25X19
PACKAGE SIZE	= 32.50X25.00mm

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



**Emulation Technology, Inc.**  
 — VLSI and SMT ADAPTERS and ACCESSORIES —  
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 TEL:(408)982-0660 FAX:(408)982-0664

SHEET: 1 OF 1	DATE: 05/24/04	REVISION: A	<b>ASSEMBLY DRAWING</b>
CHECKED: Perry Munroe	DRAWN: Huy Nguyen	ITEM: S-BCK-25-474-XX	
Scale 2:1	DO NOT SCALE DRAWING	DESCRIPTION: BCK-474-2BG025-YY	